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Chou et al.

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(54) **FLUID PROCESSING SYSTEMS INCLUDING A PLURALITY OF MATERIAL TANKS, AT LEAST ONE MIXING TANK, AT LEAST ONE HOLDING TANK, AND RECIRCULATION LOOPS**

(58) **Field of Classification Search**
CPC B01F 13/1055; B01F 15/00194; B01F 15/0022; B01F 15/00227; B01F 15/00285;
(Continued)

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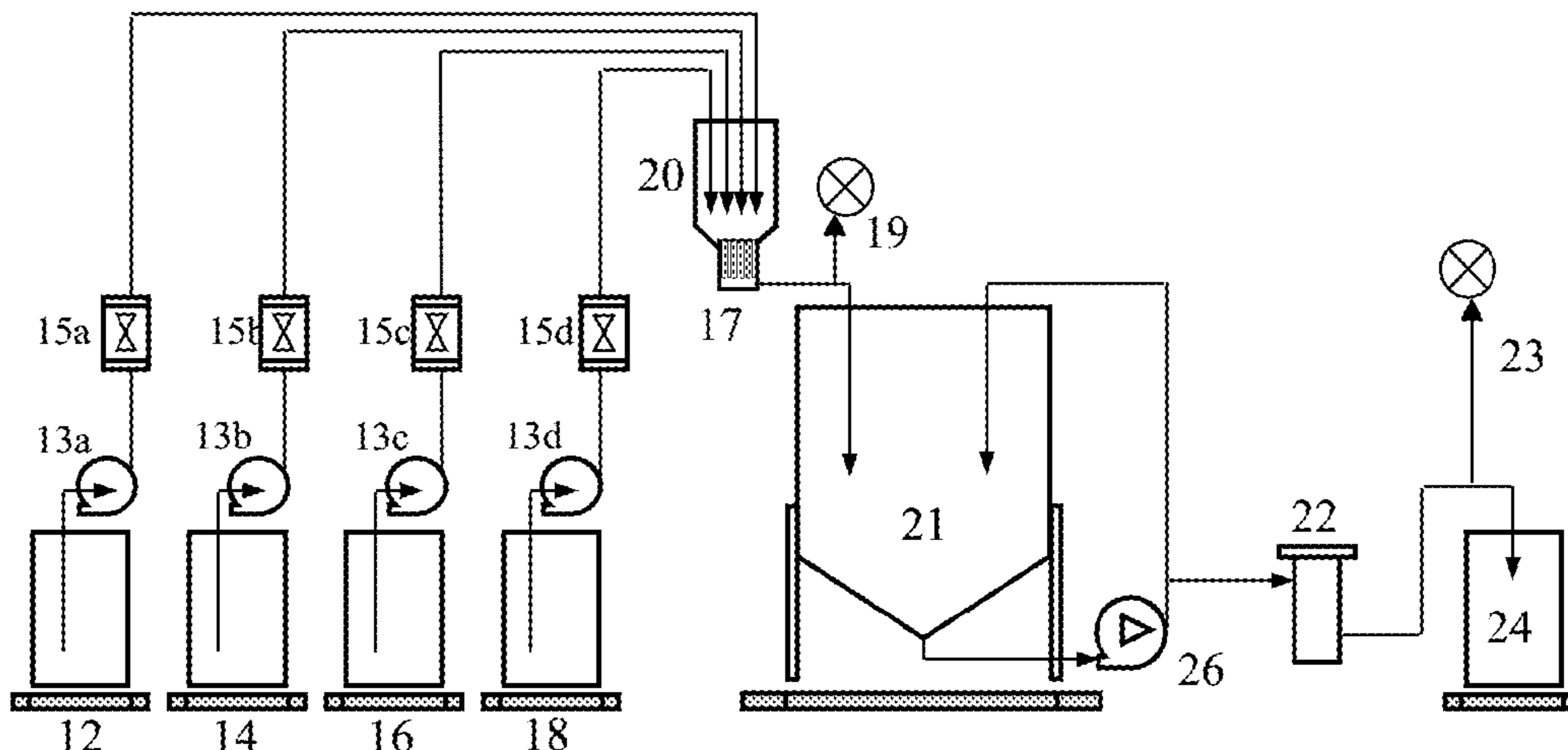
Related U.S. Application Data

(63) Continuation of application No. 15/432,099, filed on Feb. 14, 2017, now Pat. No. 10,159,949.
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(57) **ABSTRACT**
The disclosure features a system that includes a plurality of material tanks, each of which includes at least one material for forming a chemical composition and includes a first recirculation loop; at least one mixing tank in which the materials from the material tanks are mixed to form a chemical composition, the mixing tank including a second recirculation loop; and at least one holding tank configured to continuously receive the chemical composition from the mixing tank, the holding tank including a third recirculation loop. The system may further include a plurality of fluid flow controller units and be configured to form material and chemical composition flows in an in-process steady state.

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(52) **U.S. Cl.**
CPC **B01F 33/84** (2022.01); **B01F 23/45** (2022.01); **B01F 23/49** (2022.01); **B01F 23/511** (2022.01);
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16 Claims, 4 Drawing Sheets



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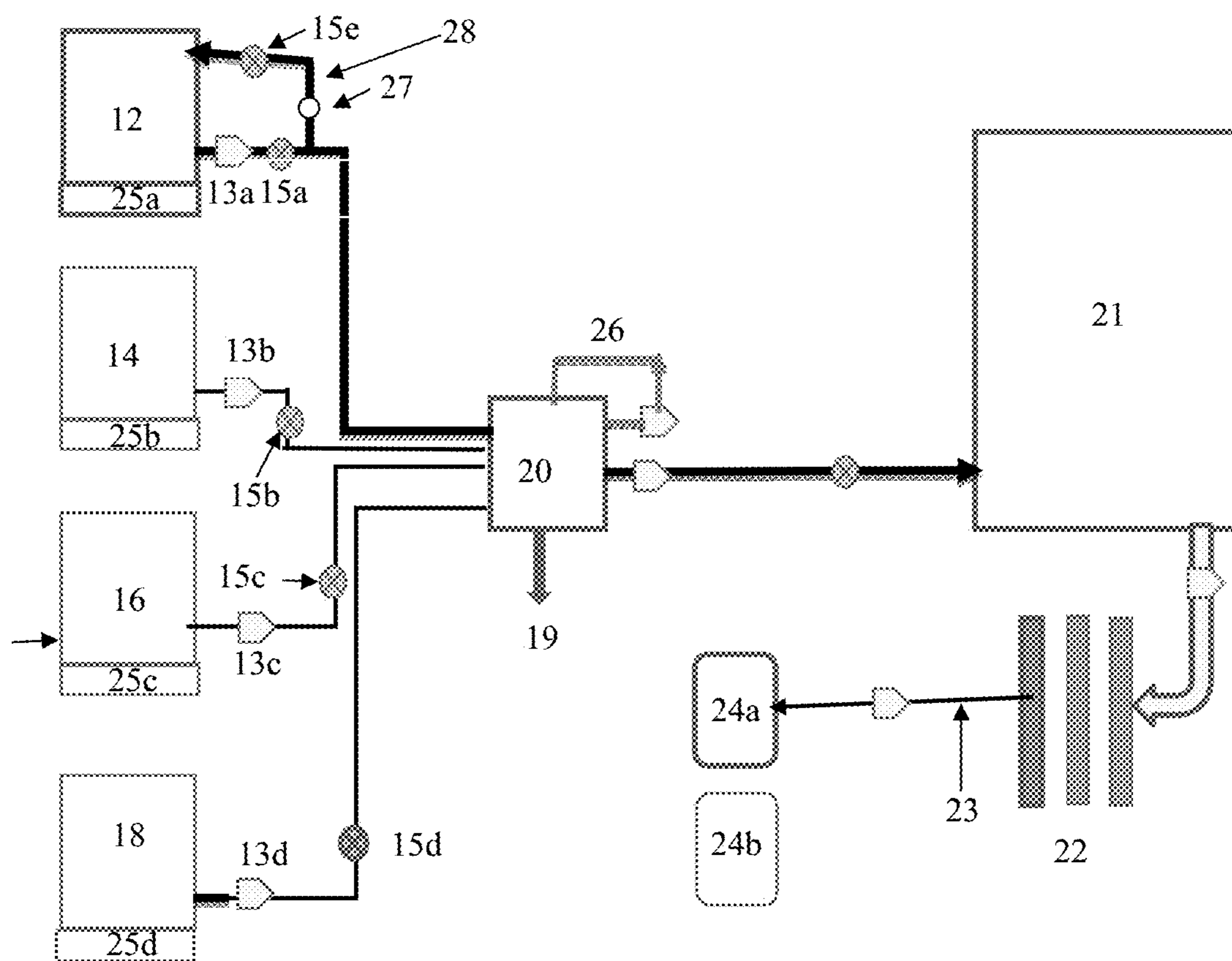


Figure 1

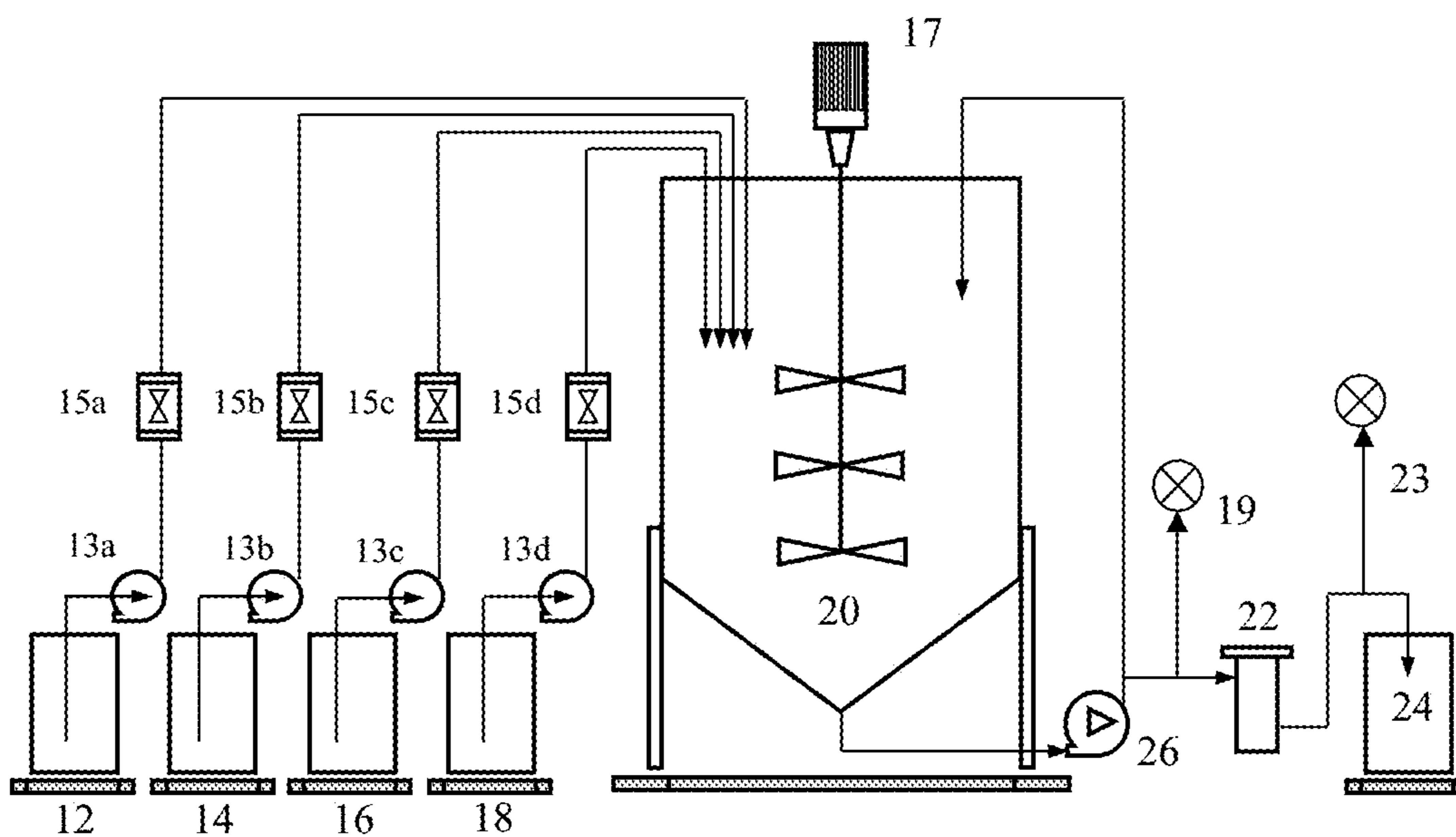


Figure 2
--PRIOR ART --

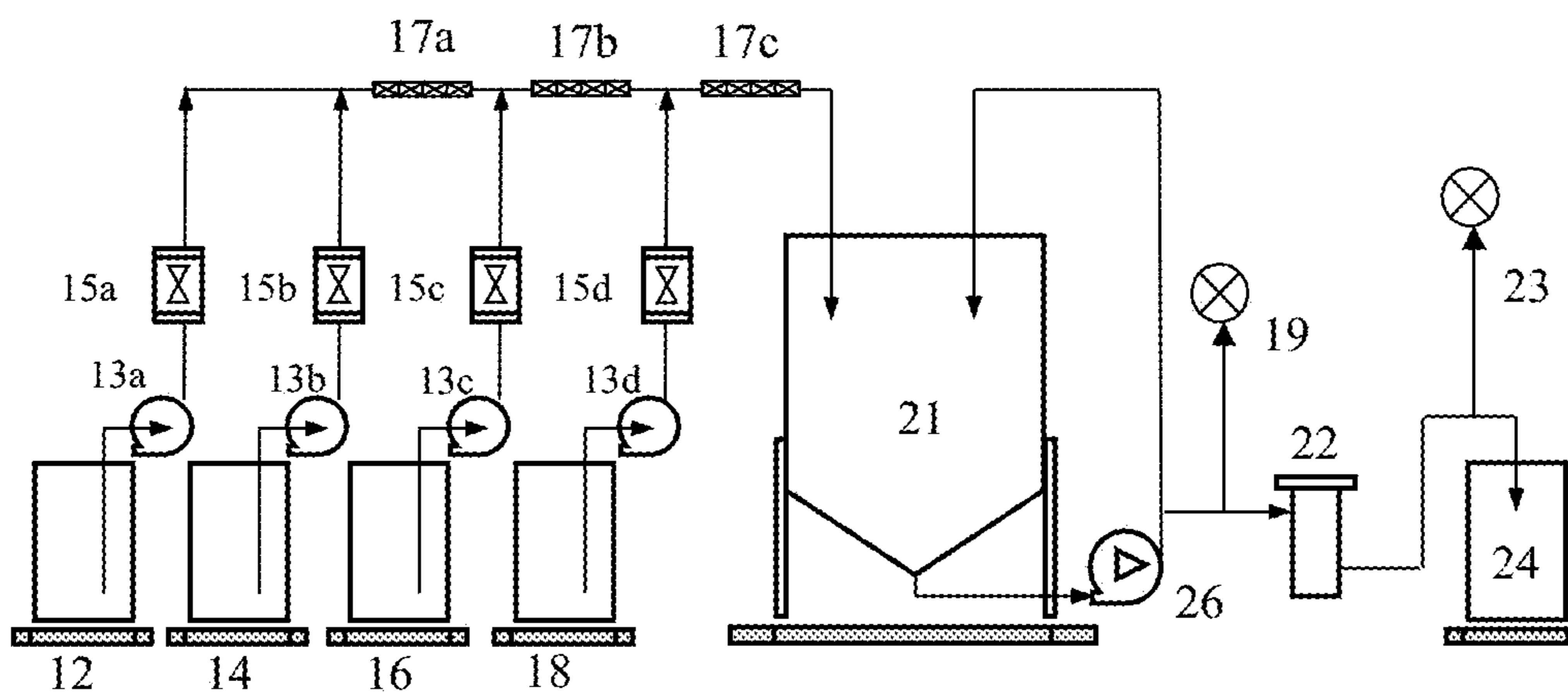


Figure 3
-- PRIOR ART --

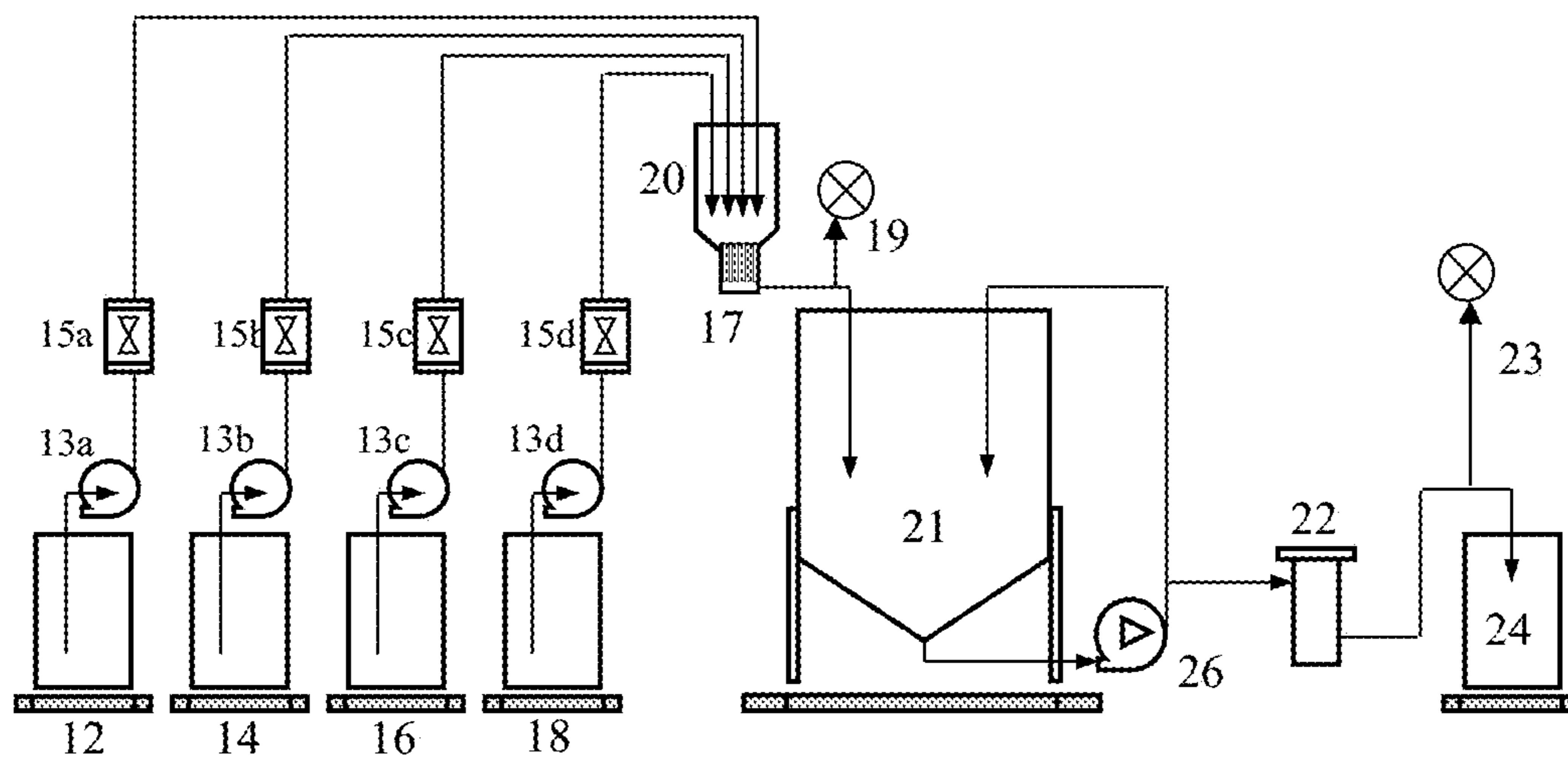


Figure 4

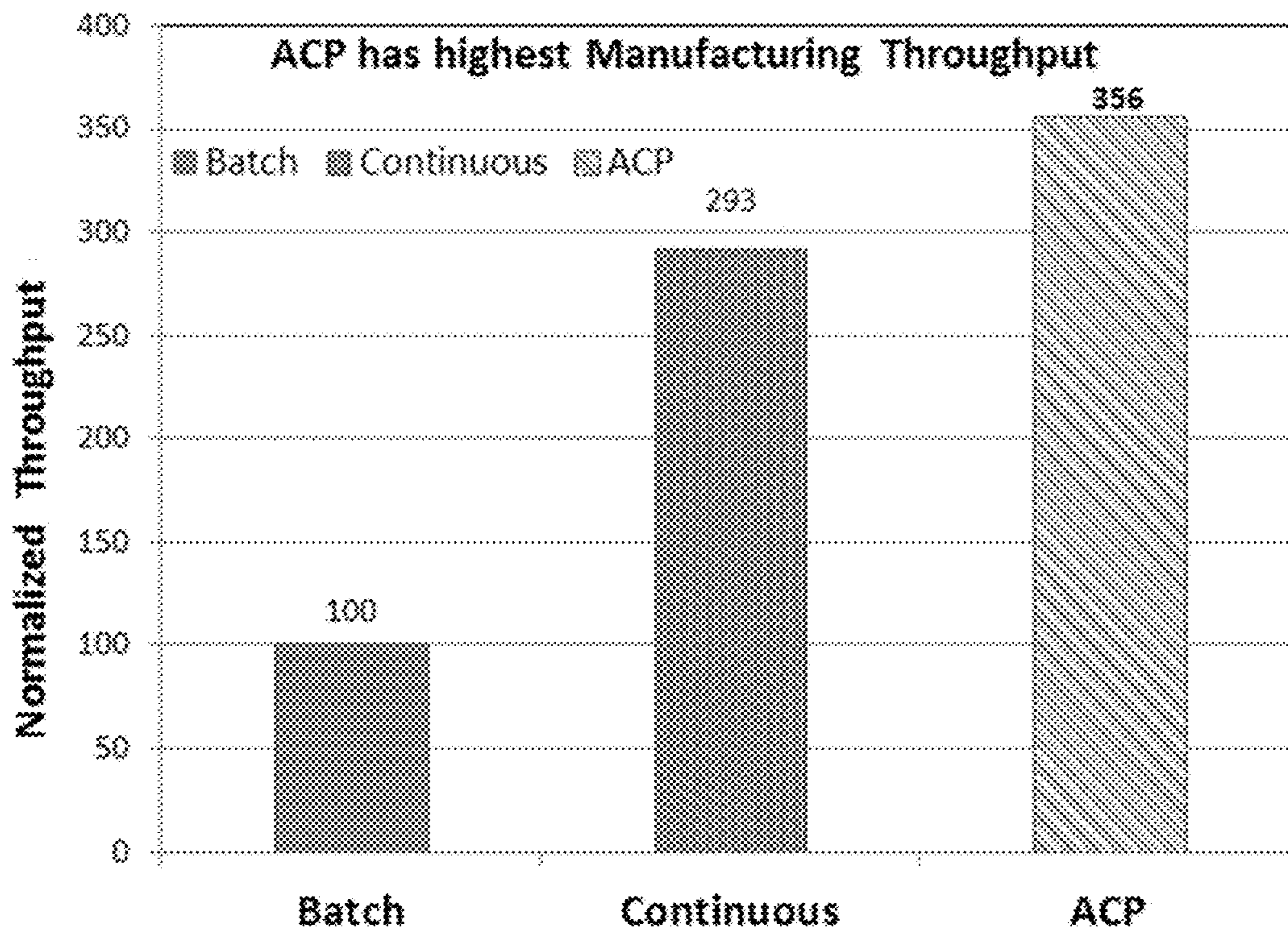


Figure 5

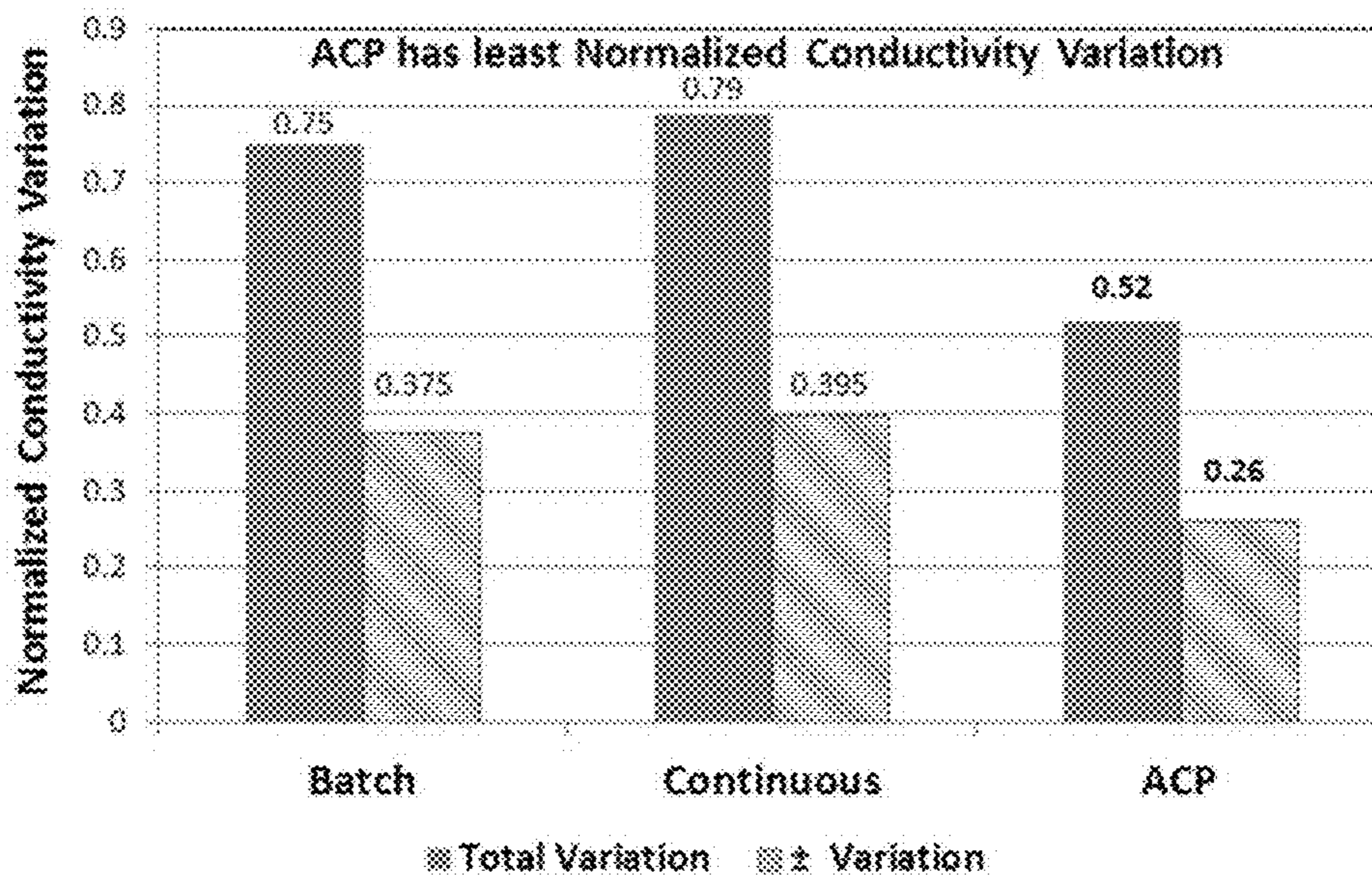


Figure 6

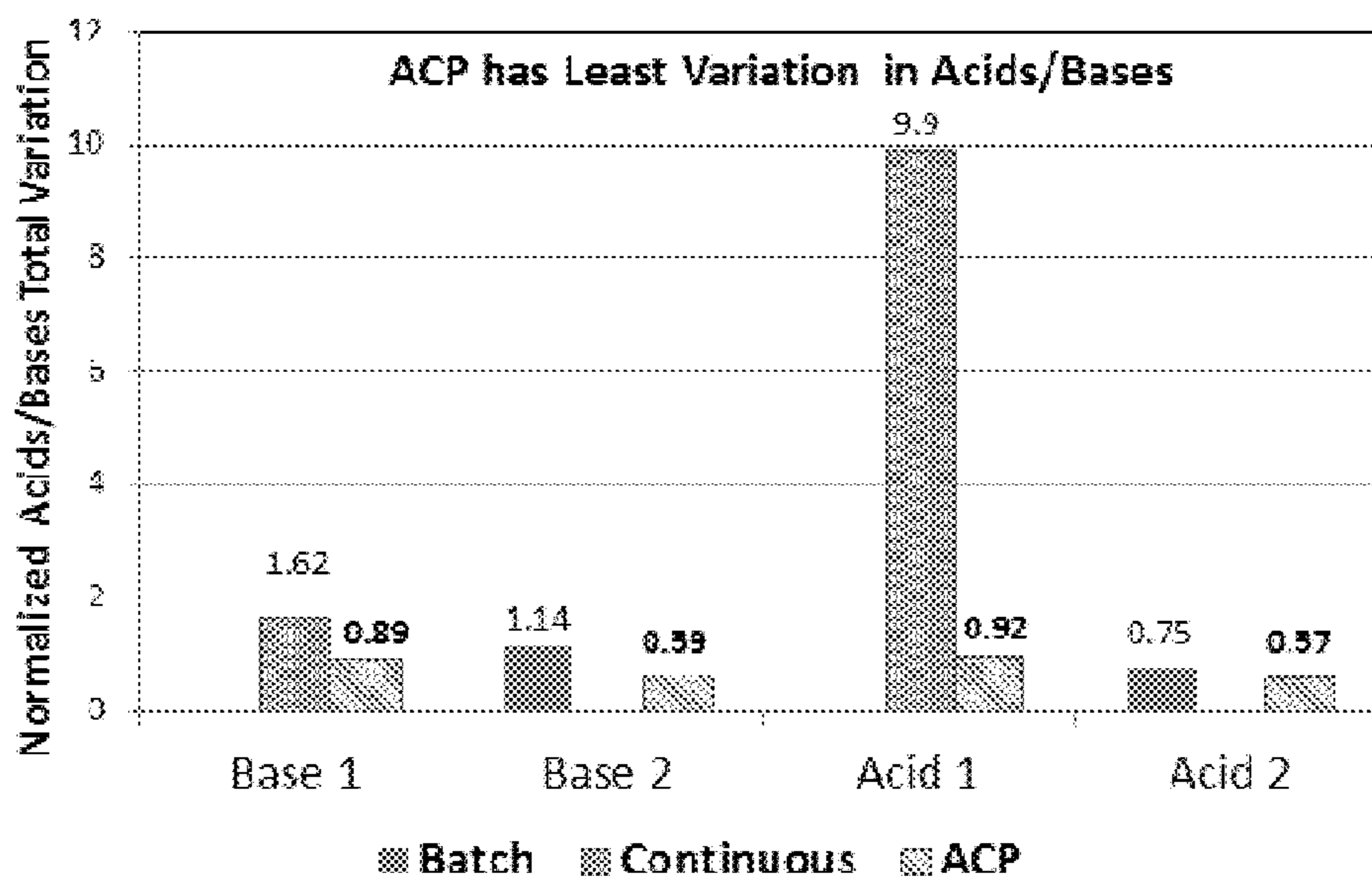


Figure 7

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**FLUID PROCESSING SYSTEMS INCLUDING
A PLURALITY OF MATERIAL TANKS, AT
LEAST ONE MIXING TANK, AT LEAST ONE
HOLDING TANK, AND RECIRCULATION
LOOPS**

CROSS-REFERENCE TO RELATED
APPLICATIONS

The present application is a continuation of U.S. Utility application Ser. No. 15/432,099, filed on Feb. 14, 2017, which claims priority to U.S. Provisional Application Ser. No. 62/306,795, filed on Mar. 11, 2016. The contents of the parent applications are hereby incorporated by reference in their entirety.

TECHNICAL FIELD

This disclosure relates to methods of continuous fluid processing, as well as related systems and components.

BACKGROUND

Mixing is a process in which two or more substances are combined while the chemical properties of each substance remain largely unchanged. The properties of the overall mixture, however, can differ from those of the component substances. Thus, mixing is often used to produce a medium with a desired set of physical and chemical properties which can be confirmed by analytical techniques.

For example, in semiconductor fabrication, chemical mechanical planarization/polishing (CMP) is used to make wafer surfaces flat. This process requires use of a slurry containing abrasive particles dispersed in a liquid chemical composition (such as those containing an acid and/or a base). The CMP slurry is typically manufactured by mixing various chemicals and abrasive particles to form a dispersion (e.g., a colloidal dispersion). During CMP, movement of the abrasive particles on the wafer mechanically removes material from the wafer surface. The acid or base in the slurry facilitates the chemical removal of material by reacting with the material to be removed. Hence, the process is called “chemical” “mechanical” polishing. To produce CMP slurries having desired properties, it can be useful to filter the CMP slurries to achieve the desired distribution of abrasive particles dispersed within the chemically reactive agents. The filtration also ensures that the end CMP product has high purity.

As the semiconductor wafers become more advanced, the features on the wafer surfaces become finer and more complex. Planarizing these complex fine features requires very tight polish processing windows. Hence the CMP process requires that the CMP slurry property specifications are very tight. This, in turn, is forcing the CMP slurry manufacturers to significantly improve their production process capability while reducing variations between lots. The conventional slurry production processes are unable to meet these stringent demands.

Conventional slurry manufacturing processes include a Batch process (FIG. 2) and a Continuous Process (FIG. 3). In a batch process, all the slurry components are added to a large tank one by one (usually by a fluid transfer unit such as a pump, and/or a flow controller unit), followed by mixing the components by an agitator type device and a QC (quality control) step. After that, the mixed slurry is sent to packaging station usually through a filter station. The batch process suffers from many drawbacks including a large environmen-

2

tal footprint, long addition and mixing times, high property variations, low throughput, and high production costs.

A conventional continuous process (FIG. 3), on the other hand, replaces the very large tanks in the batch process with smaller tanks, and introduces in-line static or dynamic mixers. The raw materials are fed into these in-line mixers one by one (but never all together in one mixer). This design allows the process to be continuous and increases the throughput. However, the in-line mixers are small and create high back pressures. Each raw material flow component loop going to the in-line mixer creates flow control issues causing significant property variations. Thus, the continuous process cannot meet the tight specification demands either.

This disclosure describes an Advanced Continuous Process and related system that addresses these shortcomings.

SUMMARY

This disclosure is based on the unexpected discovery that using a tank (e.g., a relatively small tank) in which materials (e.g., materials for producing a CMP slurry) are concurrently received and mixed in a continuous fluid process can result in reduced product variations and reduced product waste, thereby significantly increasing manufacturing efficiency, manufacturing yields, and product consistency, and reducing manufacturing costs (e.g., for producing a CMP slurry).

In one aspect, this disclosure features a method of forming a chemical composition (e.g., a polishing composition such as a CMP slurry). The method includes A) mixing a plurality of continuous material flows in at least one mixing tank to form a chemical composition, each continuous material flow comprising at least one component of the chemical composition; and B) moving a continuous flow of the chemical composition to a packaging station downstream of the at least one mixing tank. The mixing and moving steps are performed continuously, the material and chemical composition flows are in an in-process steady state; and the mixing process in the at least one mixing tank includes at least one mixing method selected from the group consisting of turbulent mixing of the material flows, mechanical agitation of the material flows, recirculation of the chemical composition, and a combination thereof.

In another aspect, this disclosure features a system that includes (1) a plurality of material tanks, each material tank being configured to receive a material used to form a chemical composition (e.g., a polishing composition such as a CMP slurry); (2) at least one mixing tank in which the materials from the material tanks are mixed to form a chemical composition, wherein the mixing tank is in fluid communication with the plurality of material tanks, the mixing tank is configured to continuously receive the materials from the material tanks and to continuously deliver the chemical composition downstream, and the mixing tank optionally includes a recirculation loop in fluid communication with the mixing tank; (3) optionally, at least one holding tank downstream from the mixing tank and in fluid communication with the mixing tank; and (4) optionally, at least one filter apparatus in fluid communication with the mixing tank, the filter apparatus being configured to receive and filter the chemical composition. The system does not include an in-line static or dynamic mixer between each material tank and the mixing tank.

Embodiments can include one or more of the following features:

In some embodiments, the method further includes obtaining a material flow having a substantially constant flow rate prior to the mixing step. In such embodiments,

obtaining a material flow having a substantially constant flow rate includes continuous recirculation of the material flow in a material tank through at least one fluid transfer unit and at least one flow control unit until a predetermined flow rate is reached.

In some embodiments, the method further includes performing an in-process quality control measurement of the chemical composition in the mixing tank without interrupting the continuous process.

In some embodiments, the method further includes measuring the amount of a component in the mixing tank to determine whether the amount is within a predetermined range. In some embodiments, the measuring step is performed without stopping the mixing or moving step.

In some embodiments, before moving the continuous flow of the chemical composition to the packaging station, the method further includes at least one step selected from the group consisting of measuring a mass flow rate of each continuous material flow, measuring the volume flow rate of each continuous material flow, and measuring a content weight in a tank that supplies a continuous material flow containing at least one component.

In some embodiments, the mixing tanking does not include a stirrer or a baffle. In some embodiments, the mixing tank has a volume of from about 40 liters to about 1,500 liters.

In some embodiments, the chemical composition is a polishing composition prepared from components including a diluent, an acid, a base, a salt, and abrasive particles.

In some embodiments, the diluent includes deionized water.

In some embodiments, the acid includes an organic acid, an inorganic acid, or a mixture thereof.

In some embodiments, the base includes potassium hydroxide, ammonium hydroxide, quaternary ammonium compounds (e.g., tetramethyl ammonium hydroxide or tetrabutyl ammonium hydroxide), monoethanol amine, diethanol amine, triethanol amine, or a mixture thereof.

In some embodiments, the salt includes potassium citrate, potassium carbonate, ammonium nitrate, ammonium sulfate, ammonium citrate, ammonium oxalate, potassium nitrate, potassium sulfate, potassium chloride, or a mixture thereof.

In some embodiments, the abrasive particles include silica (e.g., colloidal silica), ceria, titania, alumina, or a mixture thereof.

In some embodiments, the continuous flow of the chemical composition includes at most about 50 wt % silica.

In some embodiments, the continuous flow of the chemical composition has a pH of from about 2 to about 11 (e.g., from about 2 to about 9).

In some embodiments, the method further includes continuously moving the chemical composition into a holding tank prior to packaging.

In some embodiments, the method further includes filtering the continuous flow of the chemical composition before moving the continuous flow of the chemical composition to the packaging station.

In some embodiments, the continuous flow of the chemical composition exiting the mixing tank has a volume flow rate of at least about 20 liters per minute.

In some embodiments, the method forms a chemical composition having a total lot-to-to variation or a total within lot variation of at most about 1% in the weight of a component.

In some embodiments, the mixing tank includes at least one mixing system. In such embodiments, the mixing sys-

tem can include an agitator (e.g., a mechanical agitator), a vortex, a turbulent mixer, a recirculation loop, or a combination thereof.

In some embodiments, the system further includes at least one quality determination unit that is attached integrally to a system component. In such embodiments, the quality determination unit can include a pH meter, a conductivity meter, a concentration meter, or a LPC (Large Particle Count) meter.

In some embodiments, the system further includes a fluid transfer unit (e.g., a pump) in fluid communication with each material tank, the fluid transfer unit being configured to continuously transfer the material in each material tank to the mixing tank.

In some embodiments, the system further includes a fluid flow controller unit (e.g., a mass flow controller) between each material tank and the mixing tank, the fluid flow controller unit being configured to adjust the flow rate (e.g., the mass flow rate) of the material transferred from each material tank to the mixing tank.

In some embodiments, the system includes a load cell in contact with each material tank, the load cell being configured to measure the content weight in each material tank.

In some embodiments, the system further includes a holding tank in fluid communication with the mixing tank, the holding tank being configured to continuously receive the chemical composition from the mixing tank.

In some embodiments, the holding tank has a volume of from about 1,500 liters to about 20,000 liters.

In some embodiments, the system further includes the filter apparatus.

In some embodiments, the system further includes a packaging station downstream of the mixing tank, the packaging station being configured to packaging the chemical composition.

In some embodiments, the system further includes a recirculation loop in fluid communication with the mixing tank, the recirculation loop being configured to recirculate the chemical composition back to the mixing tank.

In some embodiments, the system further includes a plurality of fluid transfer units, wherein each fluid transfer unit is configured to continuously transfer a material from a system component (e.g., a material tank, a mixing tank, or a holding tank) to another system component (e.g., a mixing tank, a holding tank, or a packaging station).

In some embodiments, the system further includes at least one heating unit, wherein the heating unit is configured to independently heat a system component (e.g., a material tank, a mixing tank, or a holding tank).

Other features, objects, and advantages of the subject in this disclosure will be apparent from the description, drawings, and claims.

DESCRIPTION OF DRAWINGS

FIG. 1 is a schematic view of an embodiment of a blending system described in this disclosure. This blending system is also referred to as the ACP (Advanced Continuous Process) blending system.

FIG. 2 is a drawing of a conventional batch process.

FIG. 3 is a drawing of a conventional continuous process.

FIG. 4 is a drawing of another embodiment of the ACP blending system described in this disclosure.

FIG. 5 is a bar graph depicting normalized manufacturing throughput for three different manufacturing processes, i.e., a conventional Batch process, a conventional Continuous

5

process (CP), and an ACP process, each of which was obtained based on a 100-lot scale.

FIG. 6 is a bar graph depicting normalized conductivity lot-to-lot variations (i.e., total and \pm variations) obtained from the three different manufacturing processes referred to in FIGS. 2 to 4 based on a 100-lot scale.

FIG. 7 is a bar graph depicting normalized lot-to-lot total variations in base and acid concentrations obtained from the three different manufacturing processes referred to in FIGS. 2 to 4 based on a 100-lot scale.

Like reference symbols in the various drawings indicate like elements.

DETAILED DESCRIPTION

Semiconductor chemicals, such as the CMP slurries, wet etch formulations and other wet compositions typically should have high quality yet low-cost. The high-quality requirement is necessary to ensure high semiconductor wafer yields. Therefore, semiconductor users demand very tight specifications for the CMP slurries and other wet compositions. In high-volume chemical manufacturing, it is a major challenge to assure very tight specifications, while still keeping the costs down. Conventional batch processes (such as the one shown in FIG. 2) are typically performed in a relatively large holding tank, and do not have mixing and packaging performed continuously. In a typical Batch blending process, the individual raw materials are added to the tank one by one, which takes a very long time. Subsequently, they are usually mixed by an in-situ agitator for a period of time, followed by a quality control (QC) measurement. If the QC measurement is within specification, the blended composition is moved to filtering and packaging. Batch processes occupy a large environmental foot print, take long time, and hence are costly. Conventional continuous processes have mixing and packaging performed continuously, but typically use static in-line mixers between material tanks and a holding tank to mix the material flows. The in line mixers result in pressure drops across them and require bigger pumps to overcome these pressure drops. They can also result in component variations. Both of these conventional processes do not meet the challenges of advanced semiconductor node applications. Surprisingly, the inventors have found that the systems and methods described herein, also referred to as Advanced Continuous Process (ACP), can produce high quality and low cost chemical compositions at a high throughput, to satisfy the advanced semiconductor node applications.

In general, this disclosure relates to methods of continuous fluid processing to form a chemical composition, as well as related systems and components.

In some embodiments, the chemical composition can be a liquid-based composition (e.g., a composition containing water, one or more organic solvents, or a mixture thereof), such as those used in a semiconductor process. Examples of suitable chemical compositions that can be formed by the methods and systems described herein include polishing compositions (e.g., chemical mechanical planarization (CMP) slurries), developers (e.g., TMAH developers), etching compositions, and cleaning compositions. Examples of polishing compositions that can be prepared by the systems and methods described herein have been described, for example, in U.S. Application Publication No. 2013-0067998. Examples of etching compositions that can be prepared by the systems and methods described herein have been described, for example, in U.S. Application Publication Nos. 2015-0267112 and 2012-0231632. Examples of etch-

6

ing compositions that can be prepared by the systems and methods described herein have been described, for example, in U.S. Application Publication Nos. 2015-0159125, 2015-0159124, and 2015-0111804.

FIG. 1 illustrates an embodiment of a blending system for producing a chemical composition (e.g., a polishing composition such as a CMP slurry). As shown in FIG. 1, the system includes a plurality of material tanks 12, 14, 16, and 18, a plurality of pumps 13a, 13b, 13c, and 13d, a plurality of mass flow controllers 15a, 15b, 15c, 15d, and 15e, a mixing tank 20, an optional holding tank 21, an optional filter apparatus 22, a packaging station 24a or 24b, an optional load cell 25, and optional recirculation loops 26 and 28, and an optional switch valve 27. As will be described in further detail below, the blending system can be operated to combine the components of a polishing composition in a continuous flow process with reduced product variations, high throughput, and low product waste.

Before the ACP process fully starts by using the blending system shown in FIG. 1, all the raw materials (e.g. components of the CMP slurry) can be “stabilized” (e.g., by obtaining a material flow having a substantially constant flow rate) to ensure that the amounts of raw materials going into the mixing tank meet the predetermined amounts. In some embodiments, depending on the desired amount of each component in the final chemical composition, the substantially constant flow rates of the material flows exiting material tanks 12, 14, 16, and 18 can be different from one another. In some embodiments, the stabilizing is done by recirculating the raw materials back to their respective material tanks through one or more fluid flow controller units (e.g., mass flow controllers). Once predetermined amounts are reached, the recirculation can be turned off and the materials can be delivered to the mixing tank. For example, as shown in FIG. 1, material tank 12 includes a recirculation loop 28, which includes a switch valve 27 and a mass flow controller 15e. In some embodiments, recirculation loop 28 can include two or more mass flow controllers 15e.

Before the ACP process starts, the material in material tank 12 can go through the recirculation loop 28 by opening switch valve 27 and closing a switch valve (not shown in FIG. 1) between material tank 12 and mixing tank 20. Once a predetermined amount is reached (as measured by mass flow controller 15a or 15e), switch valve 27 is closed and the switch valve between material tank 12 and mixing tank 20 is open so that the material in material tank 12 can be delivered to mixing tank 20. Although FIG. 1 shows that only one material tank (i.e., material tank 12) has a recirculation loop 28, other material tanks (i.e., material tanks 14, 16, and 18) can each have a recirculation loop. This novel and important step reduces the variations in the mixing tank and helps establish an in-process steady state for the ACP process.

During use, the raw materials (e.g., components of a CMP slurry) are transferred from material tanks 12, 14, 16, and 18 to the package station 24 through mixing tank 20, optional holding tank 21, and optional filter apparatus 22 in a continuous flow. As used herein, “continuous flow” includes a bulk flow that is continuous in a downstream direction (e.g., a net flow rate that varies by less than about fifteen percent during steady-state operation) and/or substantially continuous in a downstream direction (e.g., a regularly pulsing flow with net movement in a downstream direction during steady-state operation).

The ACP system and process described in this disclosure are designed to achieve an in-process steady state. For

example, in this state, mass input and mass output during the process run are substantially equalized. Mass input includes the sum of the amounts of all of the raw materials going into the mixing tank. Mass output includes the amount of the fully mixed slurry product exiting the mixing tank, which enters the optional holding tank, the optional filter apparatus, or the packaging station. When a mass balance for the entire blending system is established, the raw material continuous flows and the downstream composition flows are in in-process steady state. In this state, the final composition is packaged at a steady pre-targeted rate without interruption (e.g., while the mixing tank recirculation and in line quality control measurements are being done). In general, material tanks **12**, **14**, **16**, and **18** can be any suitable tank and are configured to receive a material to form a chemical composition. In some embodiments, a material tank can include an inlet for receiving one or more of the components to be used to form the chemical composition. In some embodiments, a material tank can include an outlet for transferring the components to mixing tank **20**. In some embodiments, a material tank can have an opening that serves as both the inlet and the outlet. In some embodiments, a material tank can be the tank used by a manufacturer for supplying a component.

In some embodiments, when the system is used to manufacture a polishing composition, each material tank **12**, **14**, **16**, and **18** can receive one or more of the following materials: a diluent, an acid, a base, and an abrasive particle composition (e.g., an abrasive particle dispersion) containing abrasive particles. In such embodiments, each material tank **12**, **14**, **16**, or **18** can optionally receive one or more of the following additional materials: corrosion inhibitors (e.g., benzotriazoles, triazoles, and azoles), oxidizers (e.g., hydrogen peroxide, ammonium persulfate, silver nitrate, ferric nitrates or chlorides, per acids or salts, ozone water, potassium ferricyanide, potassium dichromate, potassium iodate, potassium bromate, vanadium trioxide, hypochlorous acid, sodium hypochlorite, potassium hypochlorite, calcium hypochlorite, magnesium hypochlorite, ferric nitrate, KMnO_4 , other inorganic or organic peroxides, or mixtures thereof), complexing agents, biocides, pH adjusters, and surfactants (e.g., cationic surfactants, anionic surfactants, nonionic surfactants, and amphoteric surfactants).

In some embodiments, a single raw material can be introduced through more than one of material tanks **12**, **14**, **16**, and **18** (e.g., to improve mixing quality). In some embodiments, any number (e.g., two, three, or four) of material tanks **12**, **14**, **16**, and **18** can be used to introduce the components to mixing tank **20**. In some embodiments, only two material tanks **12** and **14** can be used in the system shown in FIG. 1. For example, the diluent, the acid, and the base can be pre-mixed and the mixture can be introduced through material tank **12**, while the abrasive particle composition can be introduced through material tank **14**. In certain embodiments, more than four (e.g., five, six, seven or more) material tanks can be used in the system shown in FIG. 1 to introduce the components to mixing tank **20**.

As shown in FIG. 1, each pump **13a,b,c,d** is disposed between and in fluid communication with a respective material tank **12**, **14**, **16**, and **18** and a respective mass flow controller **15a,b,c,d**. Each pump **13a,b,c,d** is configured to move (e.g., continuously) a raw material from a respective material tank **12**, **14**, **16**, and **18** through a respective mass flow controller **15a,b,c,d** to mixing tank **20**. In some embodiments, pumps **13a,b,c,d** can be electro-mechanical diaphragm pumps including a sealed diaphragm with one side in fluid communication with the working fluid and the

other side in communication with a motor drive. Fluid is pumped as the motor drive flexes the diaphragm.

In some embodiments, the system can include a load cell in contact with each of material tanks **12**, **14**, **16**, and **18**, such that the load cell is configured to measure the content weight in the material tank. For example, as shown in FIG. 1, each of load cells **25a**, **25b**, **25c**, and **25d** can be disposed beneath a material tank (i.e., tank **12**, **14**, **16**, or **18**) to measure its content weight. During operation, each load cell can monitor the content weight in a material tank and can ensure that each of material tanks **12**, **14**, **16**, and **18** has enough material to be transferred to mixing tank **20**. In some embodiments, the load cell can be a hydraulic load cells, a pneumatic load cell, or a strain gauge load cell.

In some embodiments, each pump **13a,b,c,d** is in fluid communication with each material tank **12**, **14**, **16**, and **18** and can draw the respective materials from the material tanks **12**, **14**, **16**, and **18** continuously. The speed of each pump **13a,b,c,d** can be adjusted (e.g., individually adjusted) to change the volume flow rate of a material moving through the respective pump **13a,b,c,d**. In some embodiments, the speed of each pump **13a,b,c,d** can be adjusted to adjust the Reynolds number of the combined flow of the continuous material flows (e.g., flows including the diluent, the acid, the base, and/or the abrasive particle composition) in mixing tank **20**.

In some embodiments, each mass flow controller **15a,b,c,d** can include an adjustable orifice and an internal regulating valve that maintains a constant pressure drop across the orifice to achieve a constant mass flow rate. The mass flow rates through the flow controllers **15a,b,c,d** can be independently adjustable such that the raw materials can be combined in desired proportions. For example, the mass flow rates through the flow controllers **15a,b,c,d** can be adjusted to achieve a target concentration of abrasive particles dispersed within the polishing composition. In certain embodiments, the mass flow rates through the flow controllers **15a,b,c,d** can be adjusted to adjust the Reynolds number of the combined continuous material flow in mixing tank **20**.

When the system shown in FIG. 1 is used to make a polishing composition, each material tank **12**, **14**, **16**, and **18** can receive one or more of the following materials: a diluent, an acid, a base, and an abrasive particle composition.

The diluent can include, for example, deionized water. In some embodiments, as compared to water that is not deionized, the deionized water reduces ionic activity leading to the formation of salts and/or otherwise resulting in particle agglomeration. The addition of the diluent through one or more of the material tanks **12**, **14**, **16**, and **18** can facilitate the use of concentrated acid, base, and/or abrasive particle compositions, which are generally less expensive to transport than the corresponding dilute compositions.

The acid can include, for example, an organic acid (e.g., a carboxylic acid or a sulfonic acid), an inorganic acid (e.g., hydrochloric acid, nitric acid, or sulfuric acid), or a mixture thereof. For example, the acid can include a carboxylic acid (e.g., citric acid, succinic acid, acetic acid, propionic acid, or oxalic acid), hydrochloric acid, sulfuric acid, nitric acid or a mixture thereof. In some embodiments, the acid introduced through one or more material tanks **12**, **14**, **16**, and **18** can have an initial acid concentration of at least about 15% by weight and can be diluted in the continuous fluid process described herein such that the acid has a concentration of less than about 10% by weight (e.g., less than about 1% by weight) in the polishing composition.

The base can include, for example, potassium hydroxide, ammonium hydroxide, quaternary ammonium compounds

(e.g., tetramethyl ammonium hydroxide or tetrabutyl ammonium hydroxide), monoethanol amine, diethanol amine, triethanol amine, or a mixture thereof. In some embodiments, the base can be introduced through one or more of material tanks **12**, **14**, **16**, and **18** in an initial concentrated solution of at least about 15% by weight and can be diluted in the continuous fluid process described herein such that the base has a concentration of less than about 10% by weight (e.g., less than about 1% by volume) in the polishing composition.

The abrasive particle composition can include, for example, a water dispersion of silica, ceria, titania, alumina, or a mixture thereof. An example of an abrasive particle composition is colloidal silica. In some embodiments, the abrasive particle composition can include at least about 30 wt % (e.g., at least about 35 wt % or at least about 40 wt %) and/or at most about 50 wt % (e.g., at most about 45 wt % or at most about 40 wt %) of the abrasive particle (e.g., silica). In some embodiments, the polishing composition prepared from the abrasive particle compositions can include at most about 15 wt % (e.g., at most about 12 wt %, at most about 10 wt %, or at most about 8 wt %) and/or at least about 1 wt % (e.g., at least about 3 wt %, at least about 5 wt %, or at least about 7 wt %) of the abrasive particle (e.g., silica).

In some embodiments, the polishing composition can further include one or more salts. The salts can be neutral, basic, or acidic in nature. In some embodiments, the salts can be formed from the acid and base added into the polishing composition. In some embodiments, the salts can be added into the polishing composition independent of the acid and base described above. Exemplary salts that can be included in the polishing composition include carboxylate salts, sulfate salts, nitrate salts, halide salts, and phosphate salts, such as those formed with potassium or ammonium cation. For example, the salts can include potassium citrate, potassium carbonate, potassium nitrate, potassium sulfate, potassium chloride, ammonium nitrate, ammonium sulfate, ammonium citrate, ammonium oxalate.

In some embodiments, the polishing composition thus formed can have a pH ranging from at least about 2 (e.g., at least about 3, at least about 4, or at least about 5) to at most about 11 (e.g., at most about 10, at most about 9, or at most about 8).

As an example, material tanks **12**, **14**, **16**, and **18** can receive one or more of deionized water, potassium hydroxide, citric acid, and a colloidal silica dispersion having a pH of 7, which are combined, according to methods described below, into a polishing composition having a final pH of about 10.2.

As shown in FIG. 1, the blending system can include a mixing tank **20** in which the materials from material tanks **12**, **14**, **16**, and **18** are mixed to form a colloid dispersion. Mixing tank **20** is generally in fluid communication with the material tanks **12**, **14**, **16**, and **18** (e.g., through mass flow controllers **15a,b,c,d**). In some embodiments, mixing tank **20** is configured to continuously receive the materials from material tanks **12**, **14**, **16**, and **18** to form a polishing composition and continuously deliver the polishing composition downstream (e.g., to packaging station **24a** or **24b**). In some embodiments, the blending system described herein can include two or more (e.g., three or four) mixing tank **20**.

In some embodiments, mixing tank **20** can have one or more inlets for receiving materials from material tanks **12**, **14**, **16**, and **18** and at least one outlet for delivering the mixed polishing composition downstream. In some embodiments, mixing tank **20** does not include any mixing device, such as

a stirrer (e.g., a mechanic or electrical stirrer) or a baffle, in the tank. In such embodiments, the continuous material flows from material tanks **12**, **14**, **16**, and **18** can create a turbulent flow when they are introduced into mixing tank **20** and are mixed by this turbulent flow. As used herein, the “turbulent flow” is a flow that has a Reynolds numbers above about 4000. Without wishing to be bound by theory, it is believed that a turbulent flow of the materials in mixing tank **20** can facilitate formation of a stable polishing composition. In certain embodiments, mixing tank **20** may include a mixing device, such as a stirrer (e.g., a mechanic or electrical stirrer) or a baffle, in the tank. For example, FIG. 4 shows an embodiment of a blending system that includes a mixing device **17**.

In some embodiments, mixing tank **20** can include a recirculation loop **26** that is in fluid communication with mixing tank **20** and facilitates the mixing in the tank. Recirculation loop **26** can include a pipe that connects between an outlet and an inlet on mixing tank **20** such that the liquid composition in mixing tank **20** can flow out of tank **20** and back into tank **20** through recirculation loop **26**. In some embodiments, recirculation loop **26** can include a pump (not shown in FIG. 1) that controls the flow rate of the liquid stream in recirculation loop **26**. In some embodiments, the pump can shut off recirculation loop **26** so that the loop is no longer in use. In some embodiments, recirculation loop **26** can include one or more in-line mixers (e.g., static or dynamic mixers). In some embodiments, the recirculation of the chemical composition in mixing tank **20** continues throughout the ACP process (i.e., without interrupting the ACP process) to ensure thorough mixing.

In some embodiments, mixing tank **20** has a volume of from at least about 10 liters (e.g., at least about 20 liters, at least about 40 liters, at least about 50 liters, at least about 80 liters, at least about 100 liters, at least about 200 liters, at least about 500 liters, or at least about 1000 liters) to at most about 1500 liters (e.g., at most about 1200 liters, at most about 1000 liters, at most about 750 liters, at most about 500 liters, at most about 400 liters, or at most about 250 liters). Without wishing to be bound by theory, it is believed that the volume of mixing tank **20** can be generally larger than the volume of an in-line mixer (e.g., a static mixer or a dynamic mixer) typically used in a conventional continuous process such that mixing tank **20** allows the components of a polishing composition (e.g., a CMP slurry) to be combined and mixed concurrently. The lower limit on the tank volume can be decided by the amounts and flow rates of the raw materials. For example, a small mix tank volume (e.g., 10 liters) may be enough if only 2 chemicals are going into mixing tank **20** at low flow rates. Further, without wishing to be bound by theory, it is believed that the volume of mixing tank **20** can be generally smaller than the volume of a tank typically used in a conventional batch process, thereby reducing the manufacturing costs and environmental impact of the process.

During operation, the materials from material tanks **12**, **14**, **16**, and **18** can be continuously transferred into mixing tank **20** substantially at the same time, in which the materials are combined and mixed to form a chemical composition (e.g., a polishing composition). The chemical composition thus formed can be continuously moved downstream (e.g., to a filter apparatus or a package station). During the above continuous process, the amount of at least one component (e.g., the amounts of two, three, or all components) in mixing tank **20** can be measured (e.g., by using a HPLC, LC-MS, or ICP-OES, all of which are available at Thermo Fisher Scientific, Waltham, MA) in a quality control step **19**

11

to determine if it is within a predetermined range for that component. If the amount of the component is within the predetermined range, the continuous process can continue without modification. If the amount of the component is outside of the predetermined range, the amount of the component can be adjusted (e.g., by adjusting one of mass flow controllers **15a,b,c,d**) such that it falls within the predetermined range. In addition to the amount of the components, other quality-related parameters can also be measured using a sample from the mixing tank. These parameters include, but are not limited to, pH, conductivity, density, and mean particle size. Based on these measurements, further adjustments to material flows can be performed, if necessary. In some embodiments, such an in-process quality control measurement of the chemical composition in mixing tank **20** can be performed without interrupting the continuous process. In some embodiments, such an in-process quality control measurement can be performed by using at least one quality determination unit that is attached integrally to mixing tank **20**. Examples of quality determination units include a pH meter, a conductivity meter, a concentration meter, and a LPC (Large Particle Count) meter. Such quality determination units can be attached integrally to other system components (such as a material tank, a hold tank, a filtering apparatus, or a connecting pipe) to perform in-process quality control measurements.

Without wishing to be bound by theory, it is believed that using mixing tank **20** in a continuous process can result in reduced product variations and reduced product waste compared to a conventional continuous process (such as a continuous process in which the components of a polishing composition are mixed one by one sequentially using an in-line mixer (e.g., an in-line static or dynamic mixer) between material tanks and a holding tank) or a conventional batch process. For example, the inventors surprisingly found that the polishing composition made by the ACP system shown in FIG. **1** can have a total lot-to-lot variation or a total within lot variation of at most about 1% (e.g., at most about 0.9%, at most about 0.8%, at most about 0.7%, at most about 0.6%, at most about 0.5%, at most about 0.4%, at most about 0.3%, at most about 0.2%, or at most about 0.1%) in the weight of a component (e.g., each component) and/or a quality-related parameter (e.g., pH, conductivity, density, and mean particle size). As used herein, the term “lot-to-lot variation” refers to the variations in a parameter of the final product between different lots (e.g., average variations from one lot to another lot). As used herein, the term “within lot variation” refers to the variations in a parameter of the final product within a particular lot (e.g., average variations from one package to another package). As used herein, the term “total variation” refers to the difference between the highest variation and the lowest variation for a given parameter. For example, the polishing composition thus prepared can have a total lot-to-lot variation of at most about 0.5% in the weight of at least one component or in at least one quality-related parameter (e.g., pH, conductivity, density, and mean particle size). By contrast, the systems and methods used in a conventional continuous process or a conventional batch process typically produce a product having a total lot-to-lot variation significantly higher than 0.5% in the weight of a component or a quality-related parameter (e.g., pH, conductivity, density, and mean particle size).

In some embodiments, the blending systems described herein do not include an in-line mixer (such as a static or dynamic mixer) between material tanks **12, 14, 16, and 18** and mixing tank **20**. An in-line mixer typically includes a

12

mixing device (e.g., a baffle), has only one inlet and one outlet, and has a small volume (e.g., at most about 10 liters). Such an in-line mixer typically is not designed to mix three or more components at the same time and therefore is significantly different from mixing tank **20** (which can mix three or more components at the same time). In some embodiments, the systems described herein can include one or more in-line mixers at locations other than between material tanks **12, 14, 16, and 18** and mixing tank **20**, such as in optional recirculation loop **26** or **28**.

In some embodiments, the blending system shown in FIG. **1** can include an optional filter apparatus **22**. For example, when manufacturing a polishing composition (e.g., a CMP slurry), the system can include filter apparatus **22** to filter the polishing composition exiting mixing tank **20** to remove agglomerated particles or impurities. Details of the filters that can be used as filter apparatus **22** are provided, for example, in U.S. patent application Ser. No. 12/702,602, titled “Fluid Processing,” filed on Feb. 9, 2010, and published as U.S. Patent Application Pub. 2010/0320127 A1, the entire contents of which are incorporated herein by reference. The filter apparatus can be either Depth/Profile filters with various pore ratings or Membrane filters. The filtration media for Depth filters are typically made from polypropylene, whereas the filtration media for Membrane filters are typically made from Nylon. The filters can be purchased from commercial sources, such as Pall Corporation (Port Washington, NY), Entegris Inc. (Billerica, MA), and Roki America Co. Ltd. (Findlay, OH).

In some embodiments, an optional quality control step **23** can be performed to analyze the contents of the filtered polishing composition (e.g., to determine whether the amount of a component in the filtered polishing composition is within a predetermined range). If the filtered polishing composition meets the targeted specification, it can then flow to packaging station **24a** or **24b**. In some embodiments, at packaging station **24a** or **24b**, the polishing composition can be either used directly (e.g., in a CMP process to smooth wafers) or packaged for future use (e.g., at another location).

In some embodiments, when the ACP systems described herein are used to manufacture a chemical composition (e.g., a developer, an etching composition, or a cleaning composition) that does not contain particles or contain particles but their number and/or size are not of concern, filter apparatus **22** can be omitted or can be membrane type (absolute) filters which are much finer and suited for filtration of fine chemical formulations.

In some embodiments, the blending system described in FIG. **1** can include at least one (e.g., two, three, or more) optional holding tank **21**. Holding tank **21** can be disposed between mixing tank **20** and optional filter apparatus **22**, and in fluid communication with mixing tank **20** and filter apparatus **22**. In some embodiments, holding tank **21** can be configured to continuously receive the polishing composition from mixing tank **20**. In some embodiments, holding tank **21** can have a relatively large volume ranging from at least about 1,500 liters (e.g., at least about 2,000 liters, at least about 4,000 liters, at least about 5,000 liters, at least about 6,000 liters, at least about 8,000 liters, or at least about 10,000 liters) to at most about 20,000 liters (e.g., at most about 18,000 liters, at most about 16,000 liters, at most about 15,000 liters, at most about 14,000 liters or at most about 12,000 liters). In some embodiments, holding tank **21** can be used as a storage tank to store the polishing composition formed in mixing tank **20**. In some embodiments, holding tank **21** can be used to control the quality of the polishing composition formed in mixing tank **20**. For example, if it is

13

unclear whether the polishing composition formed in mixing tank 20 meets the targeted specification, the polishing composition can be first moved to holding tank 21 where its contents are measured. Once it is confirmed that the polishing composition in holding tank 21 meets the targeted specification, the dispersion can be transferred to filter apparatus 22 and/or packaging station 24.

In some embodiments, the system shown in FIG. 1 can include an optional pump between mixing tank 20 and optional holding tank 21, between optional holding tank 21 and optional filter apparatus 22, and/or between optional filter apparatus 22 and packaging station 24. Such a pump can be in fluid communication with these components to facilitate transfer of a fluid between these components and to control the volume flow rate of the fluid.

In some embodiments, the system shown in FIG. 1 can include an optional mass flow controller between mixing tank 20 and optional holding tank 21, between optional holding tank 21 and optional filter apparatus 22, and/or between optional filter apparatus 22 and packaging station 24. Such a mass flow controller can be in fluid communication with these components to facilitate transfer of a fluid between these components and to control the mass flow rate of the fluid.

FIG. 4 illustrates another embodiment of a blending system for producing a chemical composition. As shown in FIG. 4, the system includes a plurality of material tanks 12, 14, 16, and 18, a plurality of pumps 13a, 13b, 13c, and 13d, a plurality of mass flow controllers 15a, 15b, 15c, and 15d, a mixing tank 20, a mixing device 17 attached to mixing tank 20, an optional holding tank 21, an optional filter apparatus 22, a packaging station 24, and an optional recirculation loop 26. Each of material tank 12, 14, 16, and 18 includes a load cell located (not labelled) beneath the tank.

Although the system shown in FIG. 1 has been described for the manufacturing of a polishing composition, the system can also be used to manufacturing chemical compositions other than polishing compositions, such as developers, etching compositions and cleaning compositions. One difference between the polishing composition and the other chemical compositions is that the polishing composition has particles, whereas the other chemical compositions may not have any particles. In ACP systems that manufacture chemical compositions that do not contain particles, the raw material feeds in material tanks 12, 14, 16, and 18 can include acids, bases, and diluents without the particle raw material feed.

This disclosure also features continuous methods of forming a chemical composition (e.g., a polishing composition such as a CMP slurry). The methods can include at least the following two steps: (1) mixing a plurality of continuous material flows in at least one mixing tank to form a chemical composition, each continuous material flow containing at least one component of the chemical composition; and (2) moving a continuous flow of the chemical composition to a packaging station downstream of the mixing tank. The mixing and moving steps can be performed continuously. In some embodiments, the material and chemical composition flows are in an in-process steady state such that there is a mass balance for the process during the continuous operation. In some embodiments, the mixing process in the at least one mixing tank includes at least one mixing method selected from the group consisting of turbulent mixing of the material flows, mechanical agitation of the material flows, recirculation of the chemical composition, and a combination thereof.

14

In some embodiments, before mixing the plurality of continuous material flows in the mixing tank, the methods described herein can further include providing a plurality of material tanks, each of which contains at least one component of a chemical composition and moving (e.g., continuously) a plurality of continuous material flows from the material tanks to the mixing tank. In some embodiments, the methods described herein can further include obtaining a material flow having a substantially constant flow rate (e.g., mass flow rate) prior to the mixing process in the mixing tank. For example, this can be achieved by continuous recirculation of the material flow in a material tank through at least one fluid transfer unit and at least one flow control unit until a predetermined flow rate is reached.

In some embodiments, the methods described herein can further include performing an in-process quality control measurement of the chemical composition in the mixing tank without interrupting the continuous process. For example, after the mixing step, the methods described herein can include a measuring step that measures the amount of at least one component (e.g., each component) in the mixing tank to determine whether the amount is within a predetermined range. The measuring step can be performed without stopping the mixing step (e.g., mixing components in the mixing tank to form a chemical composition) and/or the moving step (e.g., moving a continuous flow of the chemical composition to a packaging station). If the amount measured is outside the predetermined range, the amount of that component in the mixing tank can be adjusted by allowing more or less of that component to be added into the mixing tank.

In some embodiments, before moving the continuous flow of the chemical composition to the packaging station (e.g., before mixing the plurality of continuous materials flow in a mixing tank), the methods described herein can further include at least one step (e.g., two or three steps) selected from the group consisting of measuring a mass flow rate of each continuous material flow (e.g., by using a mass flow controller), measuring the volume flow rate of each continuous material flow (e.g., by using a pump), and measuring a content weight in a tank that supplies a continuous material flow containing at least one component (e.g., by using a load cell). Without wishing to be bound by theories, it is believed that these measurements can ensure that the chemical composition formed by the ACP methods described herein can have high product consistency, high yield, and reliable performance under a high throughput process.

In some embodiments, the continuous flow of the chemical composition exiting the mixing tank can have a relatively high volume flow rate, such as at least about 20 liters per minute (e.g., at least about 30 liters per minute, at least about 40 liters per minute, at least about 50 liters per minute, or at least about 60 liters per minute) and/or at most about 1,000 liters per minute (e.g., at most about 500 liters per minute, at most about 100 liters per minute, at most about 90 liters per minute, at most about 80 liters per minute, at most about 70 liters per minute, or at most about 60 liters per minute). As a result, the ACP methods described herein can have a relatively high throughput, thereby significantly increasing manufacturing efficiency and reducing manufacturing costs.

In some embodiments, before moving a continuous flow of the chemical composition to a packaging station, the methods described herein can include moving a continuous flow of the chemical composition to an optional holding tank (e.g., to ensure that the chemical composition exiting the mixing tank meets the predetermined specification).

In some embodiments, before moving a continuous flow of the chemical composition to a packaging station, the methods described herein can include an optional filtering step that includes (1) moving a continuous flow of the chemical composition to a filter apparatus and (2) filtering the chemical composition exiting from the mixing tank (e.g., to remove agglomerated particles or impurities). In such embodiments, the filtered chemical composition can then be moved to the packaging station, in which the chemical composition can be used directly or packaged into a product for future uses. In embodiments where the methods described herein do not include a filtering step, the chemical composition exiting the mixing tank can be transferred to the packaging station directly.

In some embodiments, at least two (e.g., three, four, five, or all) of the following sub-steps in the methods described herein can be performed continuously: (1) moving the plurality of continuous material flows from the material tanks to the mixing tank, (2) mixing the plurality of continuous material flows in the mixing tank to form a chemical composition, (3) moving a continuous flow of the chemical composition to an optional holding tank, (4) moving a continuous flow of the chemical composition to an optional filter apparatus, (5) optionally filtering the chemical composition, and (6) moving the chemical composition (e.g., a filtered chemical composition) to a packaging station.

In some embodiments, the ACP methods described herein can be performed by using the system illustrated in FIG. 1. Referring to FIG. 1, the ACP methods described herein can include providing a plurality of material tanks **12**, **14**, **16**, and **18**, each of which contains at least one component of a chemical composition (e.g., a polishing composition such as a CMP slurry). A plurality of continuous material flows (each containing at least one component of the chemical composition) can then be moved from material tanks **12**, **14**, **16**, and **18** to mixing tank **20** by using pumps **13a,b,c,d**. Before moving the continuous material flows to mixing tank **20**, all the raw materials (e.g. components of the CMP slurry) can go through a recirculation loop (e.g., loop **28**) to obtain a substantially constant flow rate at a desired value. In mixing tank **20**, the components can be combined and mixed continuously to form a chemical composition. The mass flow rates of the plurality of continuous material flows can be measured and adjusted continuously by using mass flow controllers **15a,b,c,d** to ensure that appropriate amounts of components are added to mixing tank **20** to form the desired chemical composition. The volume flow rate of each continuous material flow and the content weight in each material tank **12**, **14**, **16**, and **18** can also be measured and monitored to ensure the formation of the desired chemical composition.

A quality control step **19** can then be performed to measure the amount of at least one component (e.g., two, three, or all components) in mixing tank **20** to determine whether the amount is within a predetermined range. This step can be performed without interrupting the continuous method, such as stopping the other continuous steps (e.g., the mixing step or the step of moving a continuous flow of a chemical composition downstream) in the continuous methods.

When the system shown in FIG. 1 includes filter apparatus **22** (e.g., to manufacture a polishing composition), the continuous flow of the chemical composition formed in mixing tank **20** can be moved to filter apparatus **22** to filter the chemical composition. The filtered chemical composition

can then be moved to packaging station **24** where the chemical composition can be used directly or packaged into a product for future use.

Before the chemical composition is moved to packaging station **24**, an optional quality control step **23** can be performed to analyze the contents of the chemical composition (e.g., to determine whether the amount of a component in the chemical composition is within a predetermined range). If the chemical composition meets the targeted specification, it can then flow to packaging station **24**.

In embodiments where the system shown in FIG. 1 includes holding tank **21** between mixing tank **20** and filter apparatus **22**, the continuous method can include moving the continuous flow of the chemical composition from mixing tank **20** to holding tank **21** and from holding tank **21** to filter apparatus **22**.

While certain embodiments have been disclosed, other embodiments are also possible.

In some embodiments, while pumps are described in connection with the systems shown in FIGS. 1 and 4, other fluid transfer units (such as gravitational feed units, pressurized tanks, or siphon feed units) can also be used in the blending systems described in this disclosure.

In some embodiments, while mass flow controllers are described in connection with the systems shown in FIGS. 1 and 4, other fluid flow controller units (such as volume flow controllers) can also be used in the blending systems described in this disclosure.

The contents of all publications cited herein (e.g., patents, patent application publications, and articles) are hereby incorporated by reference in their entirety.

The following examples are illustrative and not intended to be limiting.

EXAMPLES

Overview of Examples 1, 2 & 3

Three representative examples are shown below. These examples compare an ACP process described in this disclosure with a conventional Batch process (also referred below as “Batch process” as shown in FIG. 2) and a conventional Continuous process (also referred below as “Continuous process” as shown in FIG. 3). For each of the three examples, test results were collected over 100 production lots.

Example 1: Production Throughput Experiment

A detailed study for throughput analysis was performed on an ACP process, a conventional Batch process, and a conventional Continuous process. The procedures for these three processes are described below.

Batch Process (Comparative)

100 lots of a polishing composition were made using a batch manufacturing process. The polishing composition contained chemicals, water and silica abrasive particles. The chemicals included a carboxylic acid (Acid 2), an organic base (Base 2), and other chemicals. As illustrated in FIG. 2, for each lot, the above chemicals and water were pumped from material tanks **12**, **14**, and **16** into a 3000 gallon tank **20** (which serves both as a mixing tank and a holding tank) one by one through pumps **13a,b,c** and mass flow controllers **15a,b,c**. The silica abrasive dispersion was then pumped from material tank **18** into the tank **20** through pump **13d** and mass flow controller **15d**. Tank **20** contained a paddle type mixer **17**, which was activated to mix all the components.

After several hours of mixing, filtration and packaging operations were initiated. Specifically, the mixed polishing composition from the tank **20** was pumped through a filter apparatus **22** (which contained several filter banks) into a packaging station **24** (which included drums or totes) that hold the finished product. Quality control was performed on the packaged polishing composition. The production throughput was measured by dividing the number of gallons packaged by the total time used to make that particular lot of polishing composition. The total time included the time to introduce all the chemicals, water and abrasive dispersion, the mixing time, and the filtration and packaging time. The normalized throughput data are summarized in FIG. **5**.

Continuous Process (Comparative)

100 lots of the polishing composition were made using a continuous static mixer blending process. The polishing composition is similar to the polish composition made from the Batch process except that it contained Acid 1 and Base 1 (instead of Acid 2 and Base 2). In this process, raw materials such as chemicals, water, and abrasive dispersion were mixed using a number of in-line static mixers. This was done sequentially as follows:

As illustrated in FIG. **3**, raw material **1** and raw material **2** were pumped from material tanks **12** and **14** into the first in-line static mixer **17a** through pumps **13a,b** and mass flow controller **15a,b**. This mixture in mixer **17a** and raw material **3** from material tank **16** were then pumped into the second in-line static mixer **17b**. This mixture in mixer **17b** and raw material **4** from material tank **18** were then pumped into the third in-line static mixer **17c**. Materials **3** and **4** were pumped into in-line mixers **17b,c** by using pumps **13c,d** and mass flow controllers **15c,d**. This continuous flow process continued until all the raw materials were mixed. Finally, the mixture thus obtained was introduced into a holding tank **21**. A quick quality control step **19** of selected parameters (e.g., conductivity) was performed and the mixed polishing composition was sent to a filter station **22** and then to a packaging station **24**. The continuous process continued until a certain number of drums or totes were filled. The production throughput was measured by dividing the number of gallons packaged by the total time of production. The normalized throughput data are summarized in FIG. **5**.

Advanced Continuous Process (ACP) of this Disclosure

100 lots of the same polishing composition were produced using the blending system described in FIG. **1** or **4**.

The production throughput for the ACP process was measured by dividing the number of gallons packaged by the production time.

The normalized throughput in gallons per unit time for the Batch, Continuous and ACP processes is shown in FIG. **5**. As can be seen in FIG. **5**, when the Batch process had a normalized throughput of 100 gallons per minute, the Continuous process had a throughput of 293 gallons per minute and the ACP process has a throughput of 356 gallons per minute. In other words, the ACP process had a throughput of about 3.5 times the throughput of the Batch process and about 1.2 times the throughput of the Continuous process. FIG. **5** clearly demonstrate that the ACP process described in this disclosure had a significantly larger throughput than the comparative Batch and Continuous processes, which would result in substantial cost-savings.

Example 2: Product Overall Quality and Production Process Consistency Experiment

A detailed study was performed to analyze the quality of the products obtained from the three processes described in

Example 1 and how process variations impacted the product quality. As stated earlier, analytical QC data/process parameters were collected for the 100 production runs of each of the three processes: Batch, Continuous and ACP. These parameters were measured for three samples for a finished lot. Thus, for each manufacturing process, since there were 100 production runs, 300 data points were collected for any parameter. The three samples in a particular lot were respectively drawn from the starting package of the lot (e.g., the first drum), the middle package of the lot, and the last package of the same lot.

In general, each component in a composition has a particular electron mobility. This electron mobility of the individual components is measured by conductivity. The overall conductivity of the composition is a sum of the individual conductivities of the components. As such, if the conductivity is consistent for multiple production lots, it suggests that there are minimal process variations and the quality of the end product is considered good. Thus, conductivity "variation" of the composition can be a key indicator of the overall product quality and production process consistency.

In this example, conductivity for each of the 100 production runs was measured for each of the three processes. The conductivity was measured using a METTLER TOLEDO S-47 pH/Conductivity Meter. The mean of the conductivity value measured by the Conductivity Meter was calculated. Thereafter, normalized conductivity variations were measured as standard deviations from this mean value for each of the 3 processes. The normalized total lot-to-lot conductivity variation and the normalized \pm lot-to-lot variation in conductivity for the Batch, Continuous and ACP processes are plotted in FIG. **6**. It should be noted that the \pm variation is half of the total variation. FIG. **6** clearly demonstrates that the ACP process was surprisingly superior compared to the two conventional manufacturing processes as the ACP process had a total lot-to-lot conductivity variation (i.e., 0.52) significantly less than the total lot-to-lot conductivity variation of the Batch process (i.e., 0.75) or the total lot-to-lot conductivity variation of the Continuous process (i.e., 0.79). Thus, the product quality from the ACP process was much superior and the ACP process had much better production process consistency when compared to the two comparative processes.

Example 3: Product Component Quality and Raw Material Feed Consistency Experiment

The semiconductor industry is very stringent in terms of consumable product quality as the consumables massively impact the yields of their end chip products. Thus, for consumables such as polishing compositions or chemical compositions, the concentrations of the individual raw components are monitored and are reported in the Certificate of Analysis accompanying the sold product. Thus, it is imperative that the quality/concentration of each product component is satisfactory, and there is minimal variation in the concentrations of individual components of the products. If the concentrations of the raw materials (e.g., acids or bases) fall out of the control limits defined by the customer, the product is not deemed as sellable and must be discarded by the vendor, resulting in product waste.

Thus, experiments were performed to determine the concentration consistency of the components of the products obtained from the three processes described in Example 1. The acid and base concentrations for the 100 production runs for each of the three processes were measured in a

sampling manner identical to that described in Example 2. To measure the concentration of an acid or base, a HPLC supplied by Thermo Fisher Scientific Company was used. Base 1 and Acid 1 were analyzed in the Continuous process, whereas Base 2 and Acid 2 were analyzed in the Batch process. For the ACP process, all four of Base 1, Base 2, Acid 1 and Acid 2 were analyzed. As can be seen from FIG. 7, the normalized acids/bases total lot-to-lot variation for the ACP was surprisingly much less than those obtained from the Batch and Continuous processes. This confirms that the ACP products have much more consistent concentrations of the individual components. Specifically, the total lot-to-lot variations of Acid 1 and Base 1 obtained from the Continuous process were 9.9 and 1.62, respectively, which were significantly higher than those obtained from the ACP process, i.e., 0.92 for Acid 1 and 0.89 for Base 1. Similarly, the total lot-to-lot variations of Acid 2 and Base 2 obtained from the Batch process were 0.75 and 1.14, respectively, which were significantly higher than those obtained from the ACP process, i.e., 0.57 for Acid 2 and 0.59 for Base 2.

Thus, this example further confirms the superiority of the ACP process over the two comparative processes.

Other embodiments are within the scope of the following claims.

What is claimed is:

1. A system, comprising:

a plurality of material tanks, each material tank comprising at least one material for forming a chemical composition and the chemical composition being a polishing composition prepared from components comprising a diluent, an acid, a base, and abrasive particles, each material tank comprising a first recirculation loop in fluid communication with a respective material tank, and the first recirculation loop is configured to recirculate a respective at least one material back to the respective material tank;

at least one mixing tank in which the materials from the material tanks are mixed to form the chemical composition, wherein the mixing tank is in fluid communication with the plurality of material tanks, the mixing tank is configured to continuously receive the materials from the material tanks and to continuously deliver the chemical composition downstream, the mixing tank has a volume of from about 10 liters to about 1500 liters, the mixing tank comprises a second recirculation loop in fluid communication with the mixing tank, and the second recirculation loop is configured to recirculate the chemical composition back to the mixing tank;

a plurality of fluid flow controller units, each respective fluid flow controller unit configured to adjust a flow rate of the respective at least one material from the respective material tank to the at least one mixing tank, wherein the flow rate is configured to provide a continuous flow of the respective at least one material and the chemical composition through the system;

at least one holding tank downstream from the mixing tank and in fluid communication with the mixing tank, wherein the holding tank is configured to continuously receive the chemical composition from the mixing tank, the holding tank comprises a third recirculation loop in fluid communication with the holding tank, and the third recirculation loop is configured to recirculate the chemical composition back to the holding tank;

optionally, at least one flow controller unit between the at least one mixing tank and the at least one holding tank, wherein the flow controller unit is configured to facili-

tate continuous transfer of the chemical composition between the at least one mixing tank and the at least one holding tank;

optionally, at least one filter apparatus in fluid communication with the mixing tank or the holding tank, the filter apparatus being configured to receive and filter the chemical composition; and

a packaging station downstream of the holding tank or the optional filter apparatus, the packaging station being configured to receive the chemical composition and package the chemical composition into a product; wherein the system is configured to form material and chemical composition flows in an in-process steady state.

2. The system of claim 1, wherein the mixing tank further comprises an agitator, a vortex, a turbulent mixer, or a combination thereof.

3. The system of claim 1, further comprising at least one quality determination unit that is attached integrally to a system component.

4. The system of claim 3, wherein the quality determination unit comprises a pH meter, a conductivity meter, a concentration meter, or a LPC (Large Particle Count) meter.

5. The system of claim 1, wherein the mixing tank has a volume of from about 40 liters to about 1500 liters.

6. The system of claim 1, further comprising a fluid transfer unit in fluid communication with each material tank, the fluid transfer unit being configured to continuously transfer the material in each material tank to the mixing tank.

7. The system of claim 1, further comprising a fluid flow controller unit between each material tank and the mixing tank, the fluid flow controller unit being configured to adjust the flow rate of the material transferred from each material tank to the mixing tank.

8. The system of claim 1, wherein the system comprises a load cell in contact with each material tank, the load cell being configured to measure the content weight in each material tank.

9. The system of claim 1, wherein the holding tank has a volume of from about 1,500 liters to about 20,000 liters.

10. The system of claim 1, wherein the system comprises the filter apparatus.

11. The system of claim 1, further comprising a plurality of fluid transfer units, wherein each fluid transfer unit is configured to continuously transfer a material from a system component to another system component.

12. The system of claim 1, further comprising at least one heating unit, wherein the heating unit is configured to independently heat a system component.

13. The system of claim 1, wherein the system comprises first, second, third, and fourth material tanks, the first material tank comprises a diluent, the second material tank comprises an acid, the third material tank comprises a base, and the fourth material tank comprises abrasive particles.

14. The system of claim 1, wherein the second recirculation loop comprises a pipe connecting an outlet and an inlet of the mixing tank.

15. The system of claim 1, wherein the third recirculation loop comprises a pipe connecting an outlet and an inlet of the holding tank.

16. The system of claim 1, wherein the system is configured to perform a process of preparing the chemical composition in which the materials received by the mixing tank and the chemical compositions exiting the mixing tank form an in-process steady state.